/ Descriptions

VRW056 ṂṂ Ŀ SQS ӕ Ṁ ч s Ⅱ ᄀ Silicon PNP transistor in a SOT-23 Plastic Package.

/ Features

` Ⅵ ɔ я ϫ ı ت ᵓ я ں Ḩ/љ 5VG4 : ; 5N Й ´

High breakdown, low $V_{CE(sat)}$,complements the 2SD1782K.

/ Applications

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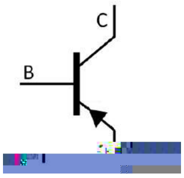
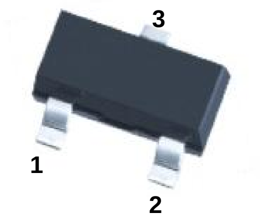
Medium power amplifier applications.

/ Equivalent Circuit



/ Pinning



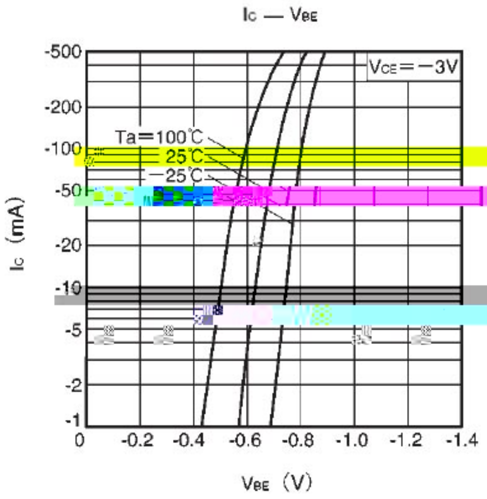
PIN1 χ Base PIN 2 χ Emitter PIN 3 χ Collector

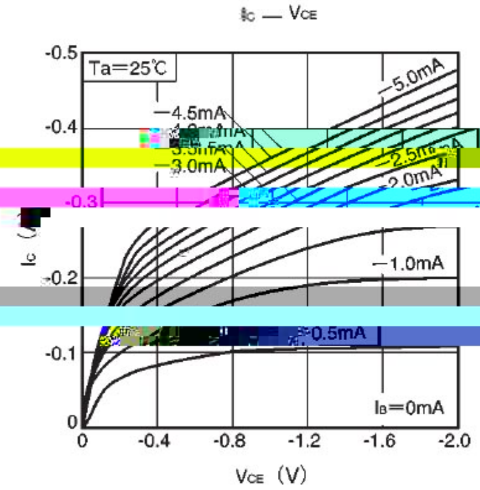
/ h_{FE} Classifications & Marking

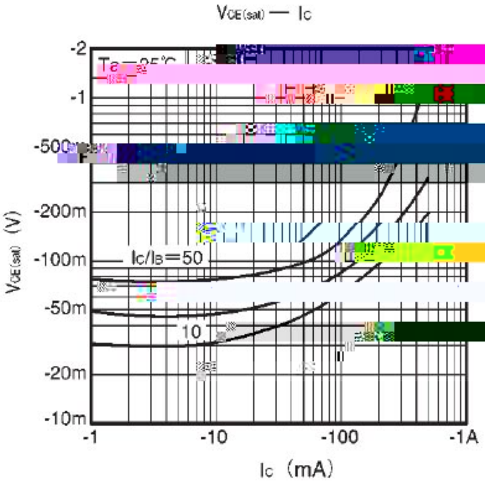
h_{FE} Classifications Symbol	Q	R
h_{FE} Range	120~270	180~390
Marking	HAKQ	HAKR

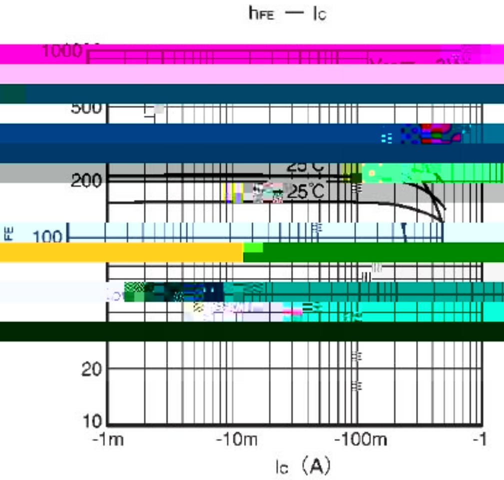
v ˝Ω̧ Parameter	˧ ᴺ Symbol	˝Ω̧Ӫ Rating	ᴅ Ꞡ Unit
Collector to Base Voltage	V_{CBO}	-80	V
Collector to Emitter Voltage	V_{CEO}	-80	V
Emitter to Base Voltage	V_{EBO}	-5	V
Collector Current - Continuous	I_C	-500	mA
Collector Power Dissipation	P_C	200	mW
Junction Temperature	T_j	150	ł
Storage Temperature Range	T_{stg}	-55 Ḱ 150	ł

/ Electrical Characteristic Curve

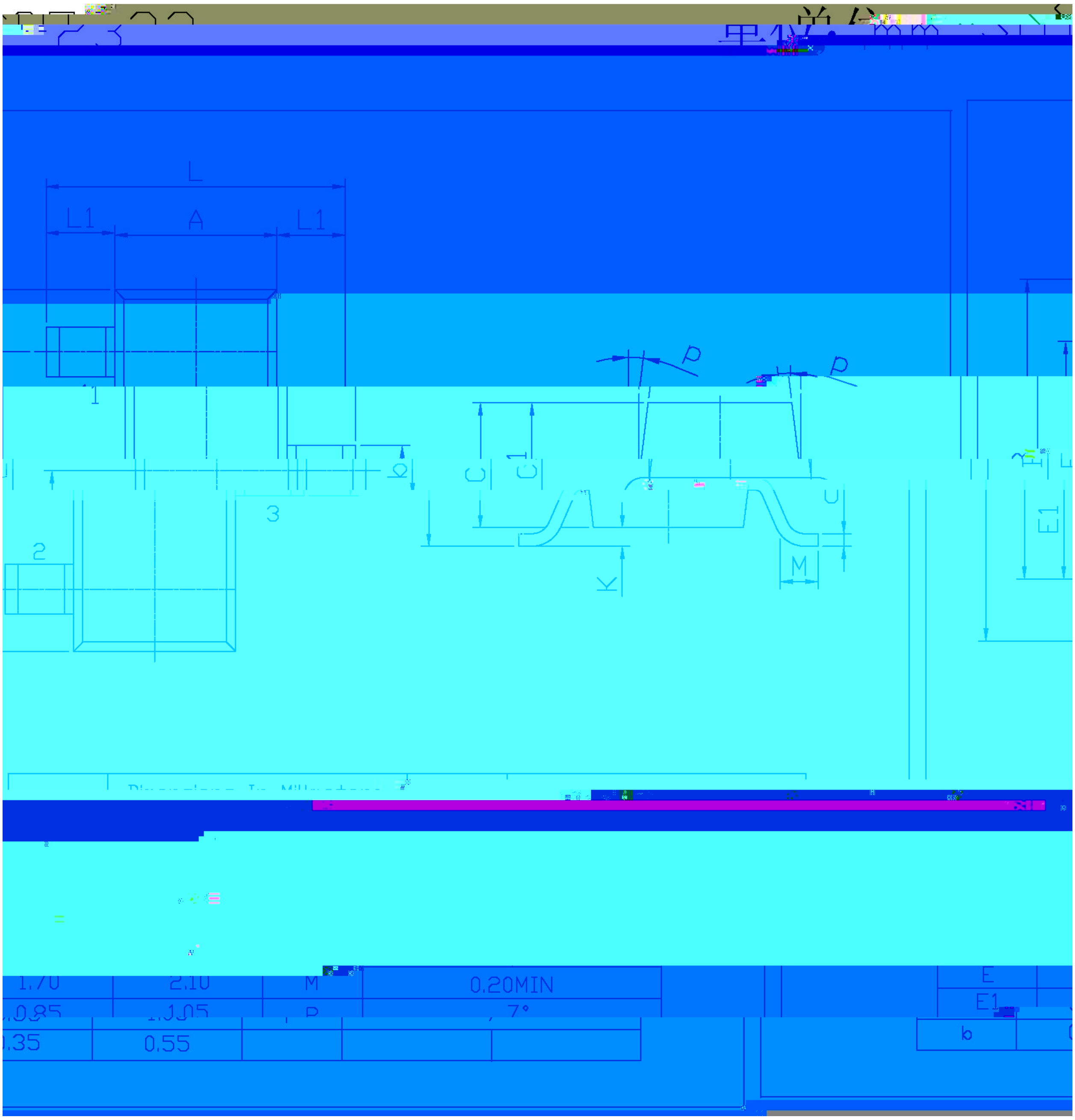








/ Package Dimensions



/ Marking Instructions

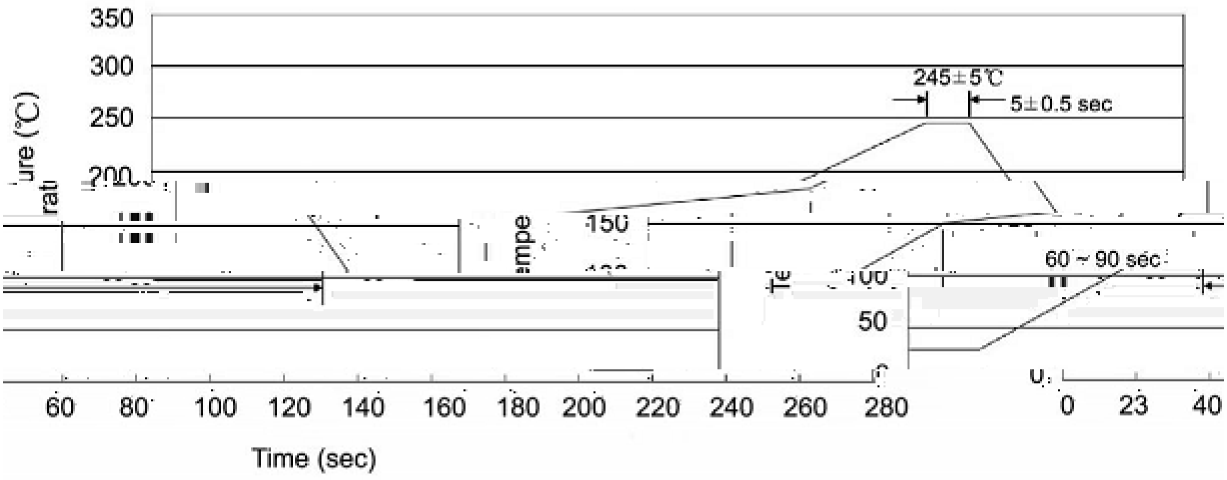
ب ˝ χ

K χ	ѬѪ ʒ ᴎ Ꮒ
DN χ	ѬѪ ʒ N Ꮒ
U χ	ѬѪ h_{FE} ˂ 6 Ꮒ

Note:

H:	Company Code
AK:	Product Type Code
R:	h_{FE} Classifications Symbol Code

( ) / Temperature Profile for IR Reflow Soldering(Pb-Free)



ب ˝ χ
1 ỉ ♬ □ ŷ 25 Ḱ 150 ł ı ˋH ڑ 60 Ḱ 90sec;
2 Š Ӫ □ ŷ 245 ° 5 ł ı ˋH ڑ ˋY ﾑ 㓒 5 ° 0.5sec;
3 ì ˙ ٱ ˛ כ ঌ ŷ 㓒 2 Ḱ 10 ł /sec.

Note:
1.Preheating:25~150 ł , Time:60~90sec.
2.Peak Temp.:245 ° 5 ł , Duration:5 ° 0.5sec.
3. Cooling Speed: 2~10 ł /sec.

/ Resistance to Soldering Heat Test Conditions

□ ŷ χ 260 ° 5 ł ˋH ڑ χ 10 ° 1 sec.

Temp.:260 ° 5 ł Time:10 ° 1 sec

/ Packaging SPEC.

ဂ ˋ ƴ ៤ / REEL

Package Type	Units					Dimension (unit mm^3)		
	Units/Reel /	Reels/Inner Box /	Units/Inner Box /	Inner Boxes/Outer Box /	Units/Outer Box /	Reel	Inner Box	Outer Box
SOT-23	3,000	10	30,000	6	180,000	7 ρ ×8	180×120×180	390×385×205

/ Notices